

(0,635mm) .025" QTS SERIES

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTS

Insulator Material: Liquid Crystal Polymer

Contact Material: Phosphor Bronze Plating:

Plating: Au or Sn over 50μ" (1,27μm) Ni Current Rating: Contact: 1.1A @ 30°C Temperature Rise Ground Plane: 7.8A @ 30°C

Temperature Rise Operating Temp: -55°C to +125°C Voltage Rating: 285 VAC Max Cycles:

100 RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0,10mm) .004" max (025-075) (0,15mm) .006" max (100) Board Stacking:

For applications requiring more than two connectors per board or 100 positions or higher, contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

- 11mm & 16mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 125 positions per row
- Edge Mount Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

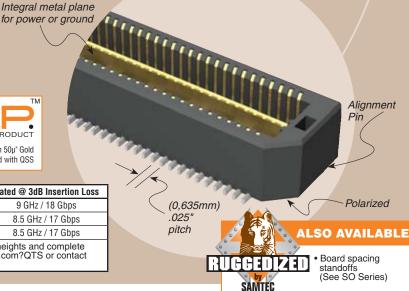


Cable Mates: SQCD



5mm Stack Height	Type	Rated @ 3dB Insertion Loss		
Single-Ended Signaling	-D	9 GHz / 18 Gbps		
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps		
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps		

Performance data for other stack heights and complete test data available at www.samtec.com?QTS or contact sig@samtec.com





-025, -050, -075, -100 (50 total positions per bank) Specify LEAD STYLE from chart.

= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

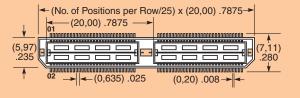
-L

= 10μ" (0,25μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C*

= Electro-Polished Selective 50μ" (1,27μm) min Au over 150μ" (3,81μm) Ni on Signal Pins in contact area, 10μ" (0,25μm) min Au over 50μ" (1,27μm) Ni on Ground Plane in contact area, Matte Tin over 50μ" (1,27μm) min Ni on all solder tails

−TR = Tape & Reel (−075 positions maximum)



(0,89)

STACK HEIGHTS				
LEAD STYLE	Α	MATED HEIGHT		
-01	(4,27) .168	(5,00) .197		
-02	(7,26) .286	(8,00) .315		
Processing conditions will affect mated height.				

Due to technical progress, all designs, specifications and components are subject to change without notice.